

FSUSB20

Low-Power 1-Port High-Speed USB (480Mbps) Switch

Features

- -30dB off isolation at 250MHz
- -30dB non-adjacent channel crosstalk at 250MHz
- 4.5Ω typical on resistance (R_{ON})
- -3dB bandwidth: >720MHz
- Low power consumption (1μA max)
- Control input: LVTTTL compatible
- Bi-directional operation
- USB high-speed and full-speed signaling capability
- Space-saving Pb-free packaging

Applications

- Cell phone, PDA, digital camera, and notebook

General Description

FSUSB20 is a low-power high-bandwidth switch specially designed for switching high-speed USB 2.0 signals in handset and consumer applications, such as cell phones, digital cameras, and notebooks with hubs or controllers with limited USB I/Os. The wide bandwidth (>720MHz) of this switch allows signals to pass with minimum edge and phase distortion. Superior channel-to-channel crosstalk results in minimal interference. It is compatible with the high-speed USB 2.0 standard.

Ordering Information

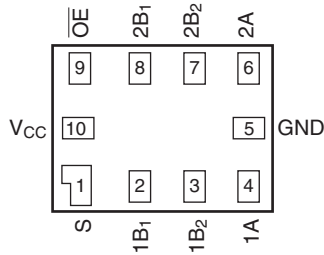
Order Number	Package Number	Pb-Free	Top Mark	Package Description
FSUSB20L10X	MAC010A	Yes	EY	10-Lead MicroPak™, 1.6 x 2.1mm
FSUSB20BQX	MLP014A	Yes	USB20	14-Terminal Depopulated Quad Very-Thin Flat Pack No Leads (DQFN), JEDEC MO-241, 2.5 x 3.0mm
FSUSB20MUX	MUA10A	Yes	FSUSB20	10-Lead Molded Small Outline Package (MSOP), JEDEC MO-187, 3.0mm Wide

Pb-Free package per JEDEC J-STD-020B.

MicroPak™ is a trademark of Fairchild Semiconductor Corporation.

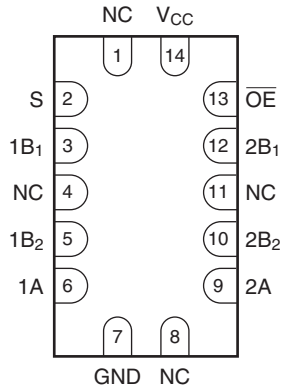
Connection Diagrams

Pad Assignments for MicroPak



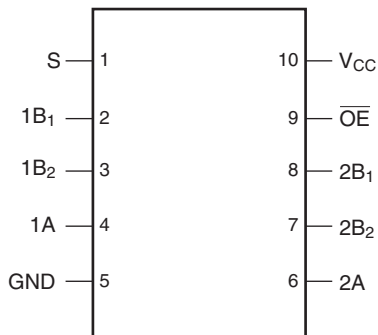
(Top View)

Pad Assignments for DQFN



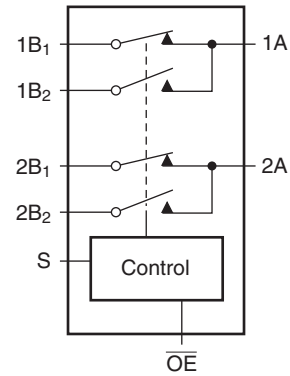
(Top Through View)

Pin Assignment for MSOP



(Top Through View)

Analog Symbol



Truth Table

S	OE	Function
X	High	Disconnect
Low	Low	A = B ₁
High	Low	A = B ₂

Pin Descriptions

Pin Name	Description
OE	Bus Switch Enable
S	Select Input
A	Bus A
B ₁ -B ₂	Bus B

Absolute Maximum Ratings

The “Absolute Maximum Ratings” are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the absolute maximum ratings. The “Recommended Operating Conditions” table will define the conditions for actual device operation.

Symbol	Parameter	Min.	Max.	Unit
V_{CC}	Supply Voltage	-0.5	+4.6	V
V_S	DC Switch Voltage	-0.5V	$V_{CC}+0.05$	V
V_{IN}	DC Input Voltage ⁽¹⁾	-0.5	+4.6	
I_{IK}	DC Input Diode Current $V_{IN} < 0V$	-50		mA
I_{OUT}	DC Output Sink Current	50		mA
I_{CC}/I_{GND}	DC V_{CC}/GND Current	± 100		mA
T_{STG}	Storage Temperature Range	-65	+150	°C
ESD	Human Body Model	All Pins	7000	V
		I/O to GND	7000	

Notes:

- The input and output negative voltage ratings may be exceeded if the input and output diode current ratings are observed.

Recommended Operating Conditions⁽²⁾

Symbol	Parameter	Min.	Max.	Unit	
V_{CC}	Power Supply Operating	3.0	3.6	V	
V_{IN}	Input Voltage	0	V_{CC}	V	
V_{OUT}	Output Voltage	0	V_{CC}	V	
t_r, t_f	Input Rise and Fall Time	Switch Control Input	0	5	ns/V
		Switch I/O	0	DC	
T_A	Free Air Operating Temperature	-40	+85°	°C	

Notes:

- Unused control inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

Typical values are at $V_{CC} = 3.0V$ and $T_A = +25^{\circ}C$.

Symbol	Parameter	Conditions	V_{CC} (V)	$T_A = -40^{\circ}C$ to $+85^{\circ}C$			Units
				Min.	Typ.	Max.	
V_{IK}	Clamp Diode Voltage	$I_{IN} = -18mA$	3.0			-1.2	V
V_{IH}	HIGH Level Input Voltage		3.0 to 3.6	2.0			V
V_{IL}	LOW Level Input Voltage		3.0 to 3.6			0.8	V
I_I	Input Leakage Current	$0 \leq V_{IN} \leq 3.6V$	3.6			± 1.0	μA
I_{OFF}	OFF-STATE Leakage Current	$0 \leq A, B \leq V_{CC}$	3.6			± 1.0	μA
R_{ON}	Switch On Resistance ⁽³⁾	$V_{IN} = 0.8V, I_{ON} = 8mA$	3.0		5.0	7.0	Ω
		$V_{IN} = 3.0V, I_{ON} = 8mA$	3.0		4.5	6.5	Ω
ΔR_{ON}	Delta R_{ON}	$V_{IN} = 0.8V, V_{IN} = 0V-1.5V, I_{ON} = 8mA$	3.0		0.3		Ω
$R_{FLAT(ON)}$	On Resistance Flatness ⁽⁴⁾	$I_{OUT} = 8mA$	3.0		1.0		Ω
I_{CC}	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND, $I_{OUT} = 0$	3.6			1.0	μA

Notes:

- Measured by the voltage drop between A and B pins at the indicated current through the switch. On resistance is determined by the lower of the voltages on the two (A or B) pins.
- Flatness is defined as the difference between the maximum and minimum value on resistance over the specified range of conditions.

AC Electrical Characteristics

Typical values are at $V_{CC} = 3.3V$ and $T_A = +25^{\circ}C$.

Symbol	Parameter	Conditions	V_{CC} (V)	$T_A = -40^{\circ}C$ to $+85^{\circ}C$			Units	Figure Number
				Min.	Typ.	Max.		
t_{ON}	Turn ON Time S-to-Bus B	$V_B = 0.8V$	3.0 to 3.6		4.8	7.0	ns	Figure 5 Figure 6
t_{OFF}	Turn OFF Time S-to-Bus B	$V_B = 0.8V$	3.0 to 3.6		2.2	4.0	ns	Figure 5 Figure 6
t_{PD}	Propagation Delay	$C_L = 10pF$	3.0 to 3.6		0.25		ns	Figure 10
O_{IRR}	Non-Adjacent OFF-Isolation	$f = 250MHz,$ $R_L = 50\Omega$	3.0 to 3.6		-26.0		dB	Figure 7
X_{TALK}	Non-Adjacent Channel Crosstalk	$f = 250MHz,$ $R_L = 50\Omega,$	3.0 to 3.6		-45.0		dB	Figure 8
BW	-3dB Bandwidth	$R_L = 50\Omega, C_L = 0pF$	3.0 to 3.6		750		MHz	Figure 9
		$R_L = 50\Omega, C_L = 5pF$			435			

USB Related AC Electrical Characteristics

Typical values are at $V_{CC} = 3.3V$ and $T_A = +25^\circ C$.

Symbol	Parameter	Conditions	V_{CC} (V)	$T_A = -40^\circ C$ to $+85^\circ C$			Units	Figure Number
				Min.	Typ.	Max.		
$t_{SK(O)}$	Channel-to-Channel Skew	$C_L = 10pF$	3.0 to 3.6		0.051		ns	Figure 10 Figure 11
$t_{SK(P)}$	Skew of Opposite Transition of the Same Output	$C_L = 10pF$	3.0 to 3.6		0.020		ns	Figure 10 Figure 11
T_J	Total Jitter	$R_L = 50\Omega$, $C_L = 10pF$ $t_R = t_F = 750ps$ at 480Mbps	3.0 to 3.6		0.170		ns	

Capacitance

Typical values are at $V_{CC} = 3.3V$ and $T_A = +25^\circ C$.

Symbol	Parameter	Conditions	$T_A = -40^\circ C$ to $+85^\circ C$		Units
			Typ.		
C_{IN}	Control Pin Input Capacitance	$V_{CC} = 0V$	2.5		pF
C_{ON}	A/B ON Capacitance	$V_{CC} = 3.3V$, $\overline{OE} = 0V$	12.0		pF
C_{OFF}	Port B OFF Capacitance	V_{CC} and $\overline{OE} = 3.3V$	4.0		pF

Typical Characteristics

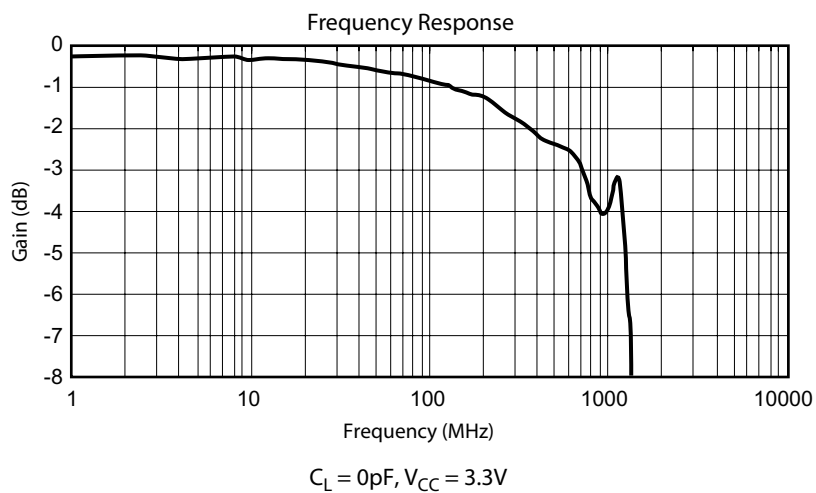


Figure 1. Gain vs. Frequency

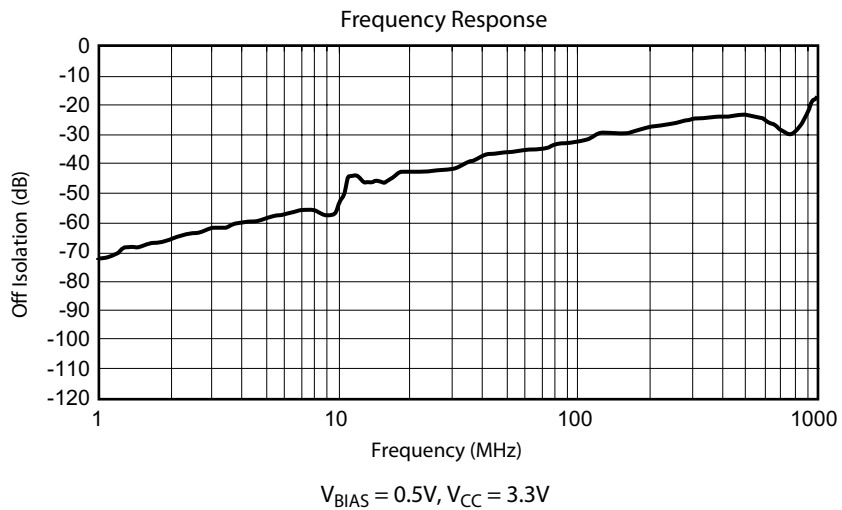


Figure 2. OFF Isolation

Typical Characteristics (Continued)

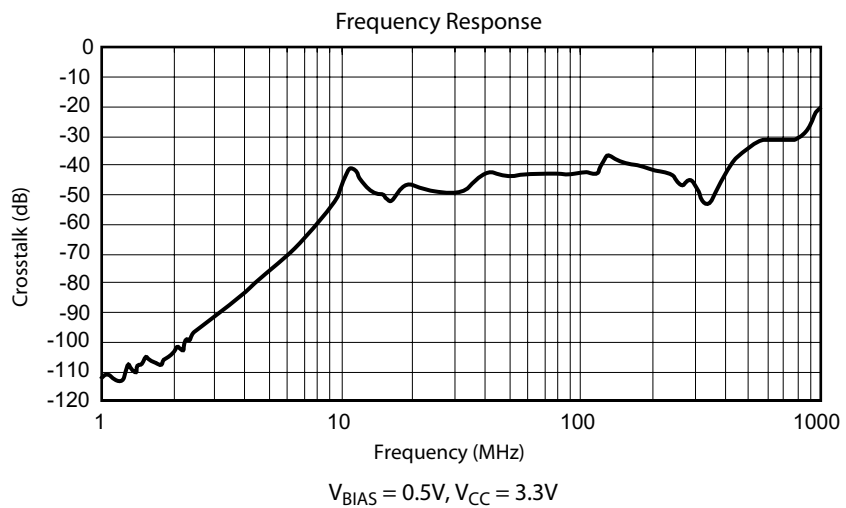


Figure 3. Crosstalk

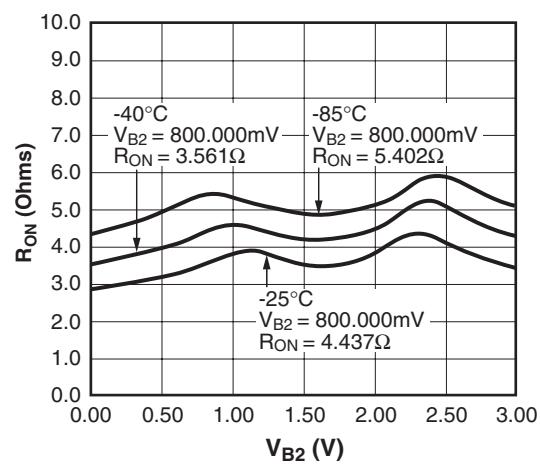
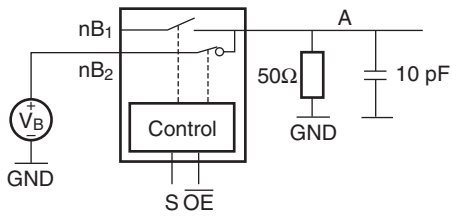


Figure 4. R_{ON}

AC Loading and Waveforms



Note: Input driven by 50Ω source terminated in 50Ω

Note: C_L includes load and stray capacitance

Note: Input PRR = 1.0 MHz, t_W = 500ns

Figure 5. AC Test Circuit

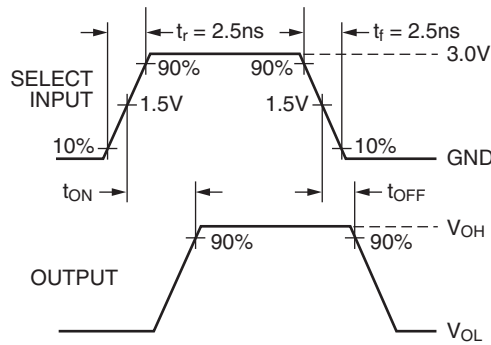


Figure 6. AC Waveforms

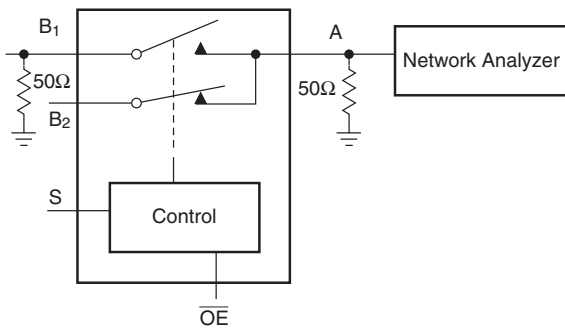


Figure 7. OFF Isolation Test

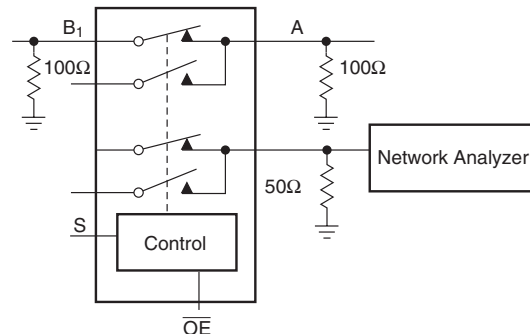


Figure 8. Crosstalk Test

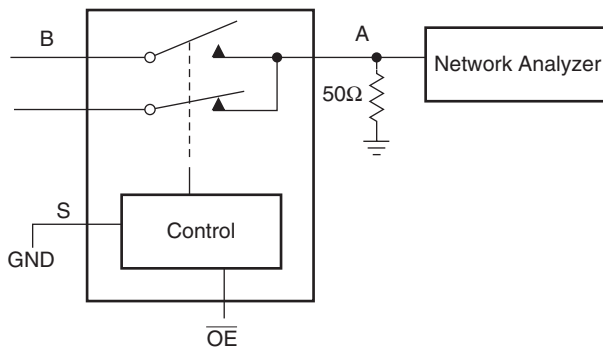


Figure 9. Bandwidth Test

AC Loading and Waveforms (Continued)

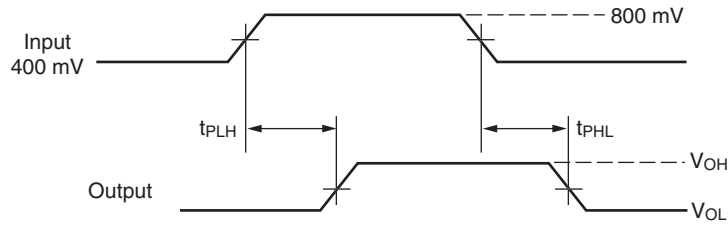


Figure 10. Propagation Delay

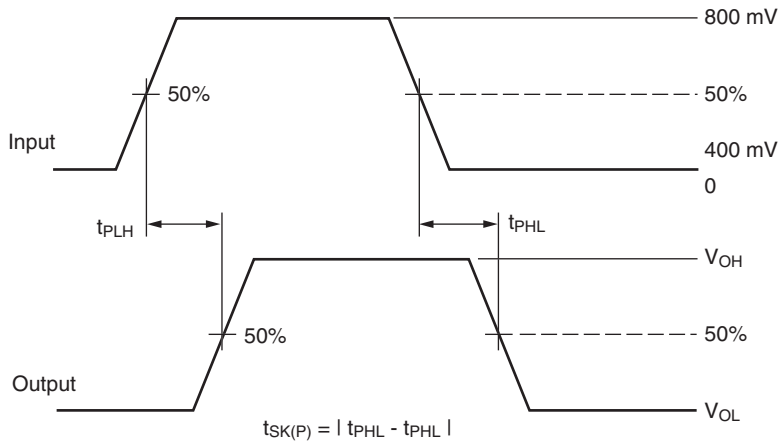


Figure 11. Pulse Skew $t_{SK(P)}$

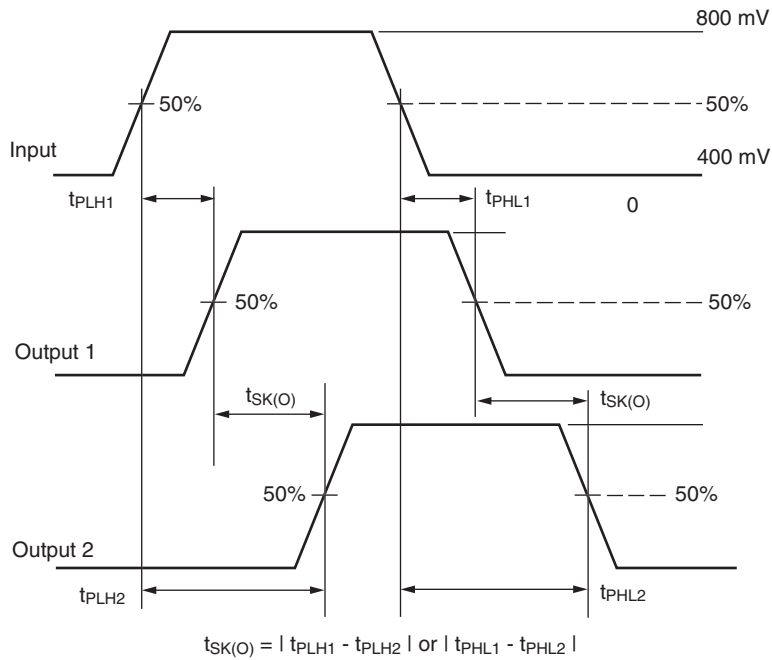


Figure 12. Output Skew $t_{SK(O)}$

Tape and Reel Specifications

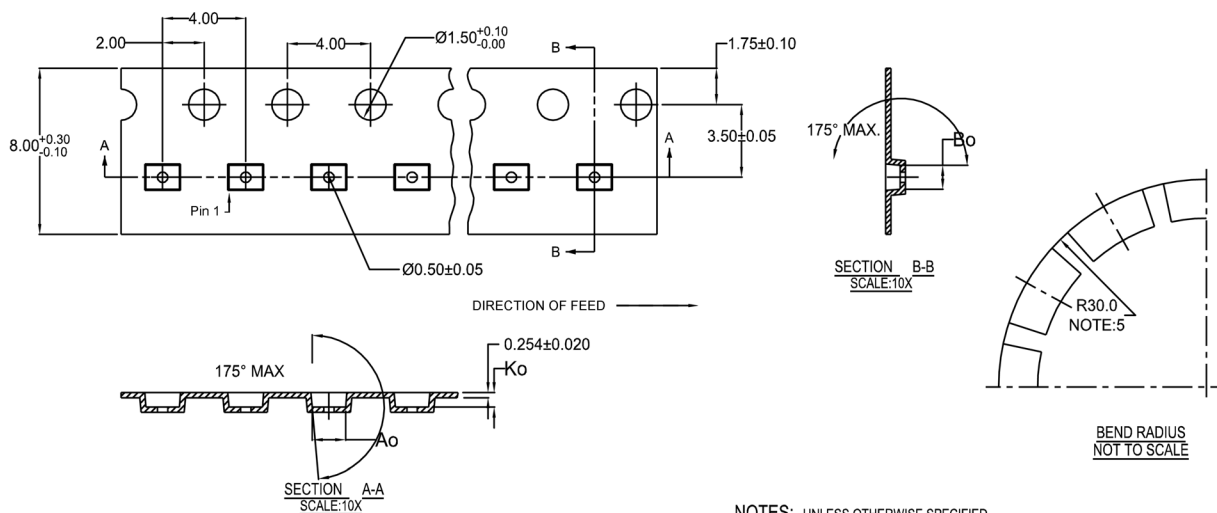
Tape Format for MicroPak

Dimensions are in millimeters unless otherwise noted.

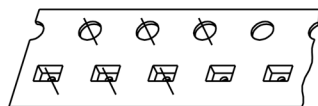
Package Designator	Tape Section	Number Cavities	Cavity Status	Cover Tape Status
L10X	Leader (Start End)	125 (typ)	Empty	Sealed
	Carrier	5000	Filled	Sealed
	Trailer (Hub End)	75 (typ)	Empty	Sealed

Tape Dimension

Dimensions are in millimeters unless otherwise noted.



10	300056	2.30 ± 0.05	1.78 ± 0.05	0.68 ± 0.05
8	300038	1.78 ± 0.05	1.78 ± 0.05	0.68 ± 0.05
6	300033	1.60 ± 0.05	1.15 ± 0.05	0.70 ± 0.05



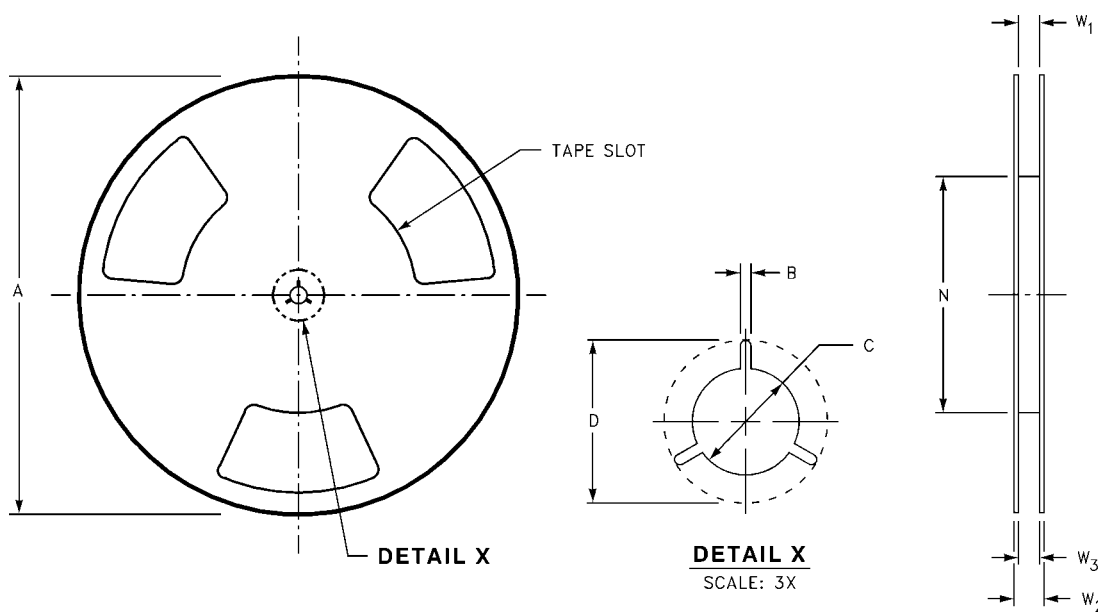
SCALE: 6X

NOTES: UNLESS OTHERWISE SPECIFIED

- ACCUMULATED 50 SPROCKETS, SPROCKET HOLE PITCH IS 200.00 ± 0.30 MM
- NO INDICATED CORNER RADIUS IS 0.127 MM
- CAMBER NOT TO EXCEED 1 MM IN 100 MM
- SMALLEST ALLOWABLE BENDING RADIUS
- POCKET POSITION RELATIVE TO SPROCKET HOLE MEASURED AS TRUE POSITION OF POCKET, NOT POCKET HOLE

Reel Dimension for MicroPak

Dimensions are in inches (millimeters) unless otherwise noted.



Tape Size	A	B	C	D	N	W1	W2	W3
(8mm)	7.0 (177.8)	0.059 (1.50)	0.512 (13.00)	0.795 (20.20)	2.165 (55.00)	0.331 +0.059/-0.000 (8.40 +1.50/-0.00)	0.567 (14.40)	W1 +0.078/-0.039 (W1 +2.00/-1.00)

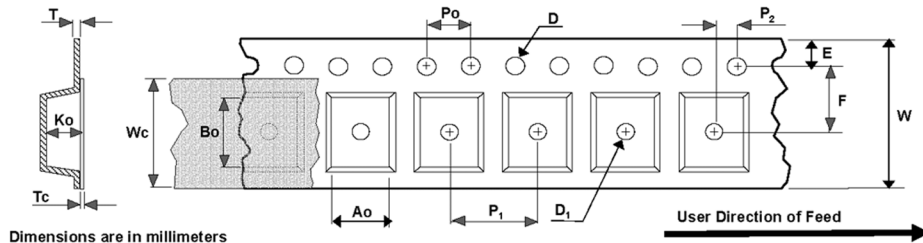
Tape Format for DQFN

Dimensions are in millimeters unless otherwise notes.

Package Designator	Tape Section	Number Cavities	Cavity Status	Cover Tape Status
BQX	Leader (Start End)	125 (typ)	Empty	Sealed
	Carrier	2500/3000	Filled	Sealed
	Trailer (Hub End)	75 (typ)	Empty	Sealed

Tape Dimensions

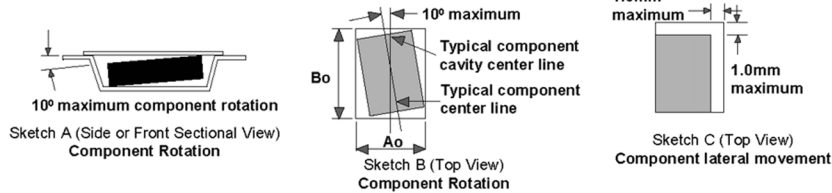
Dimensions are in millimeters unless otherwise noted.



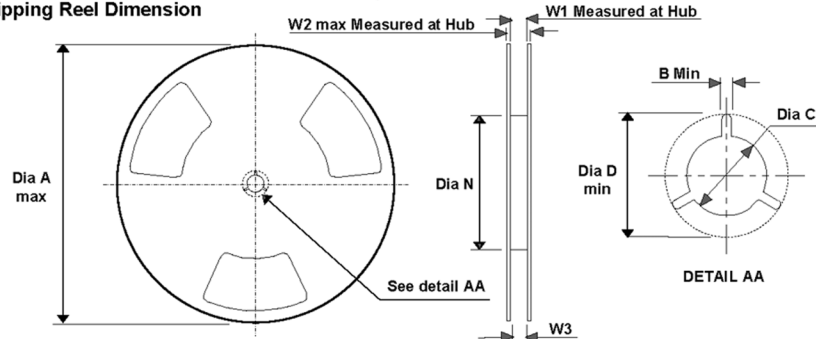
Dimensions are in millimeters

Package	Ao +/-0.10	Bo +/-0.10	D +/-0.05	D1 min.	E +/-0.1	F +/-0.1	Ko +/-0.1	P1 TYP	Po TYP	P2 +/-0.05	T TYP	Tc +/-0.005	W +/-0.3	Wc TYP
2 x 2	2.30	2.30	1.55	1.0	1.75	3.5	1.0	8	4	2.0	0.3	0.07	8	5.3
2.5x2.5	2.80	2.80	1.55	1.5	1.75	5.5	0.9	8	4	2.0	0.3	0.07	12	9.3
2.5x3.0	2.80	3.30	1.55	1.5	1.75	5.5	0.9	8	4	2.0	0.3	0.07	12	9.3
2.5x3.5	2.80	3.80	1.55	1.5	1.75	5.5	0.9	8	4	2.0	0.3	0.07	12	9.3
2.5x4.5	2.80	4.80	1.55	1.5	1.75	5.5	0.9	8	4	2.0	0.3	0.07	12	9.3
3.5x4.5	3.80	4.80	1.55	1.5	1.75	5.5	0.9	8	4	2.0	0.3	0.07	12	9.3
2.5x3.0	2.80	3.30	1.55	1.5	1.75	5.5	0.9	8	4	2.0	0.3	0.07	12	9.3
4 x 4	4.35	4.35	1.55	1.5	1.75	5.5	1.1	8	4	2.0	0.3	0.07	12	9.3
5 x 5	5.35	5.35	1.55	1.5	1.75	5.5	1.1	8	4	2.0	0.3	0.07	12	9.3
6 x 6	6.30	6.30	1.55	1.5	1.75	7.5	1.1	12	4	2.0	0.3	0.07	16	13.3

Notes: Ao, Bo, and Ko dimensions are determined with respect to the EIA /Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).



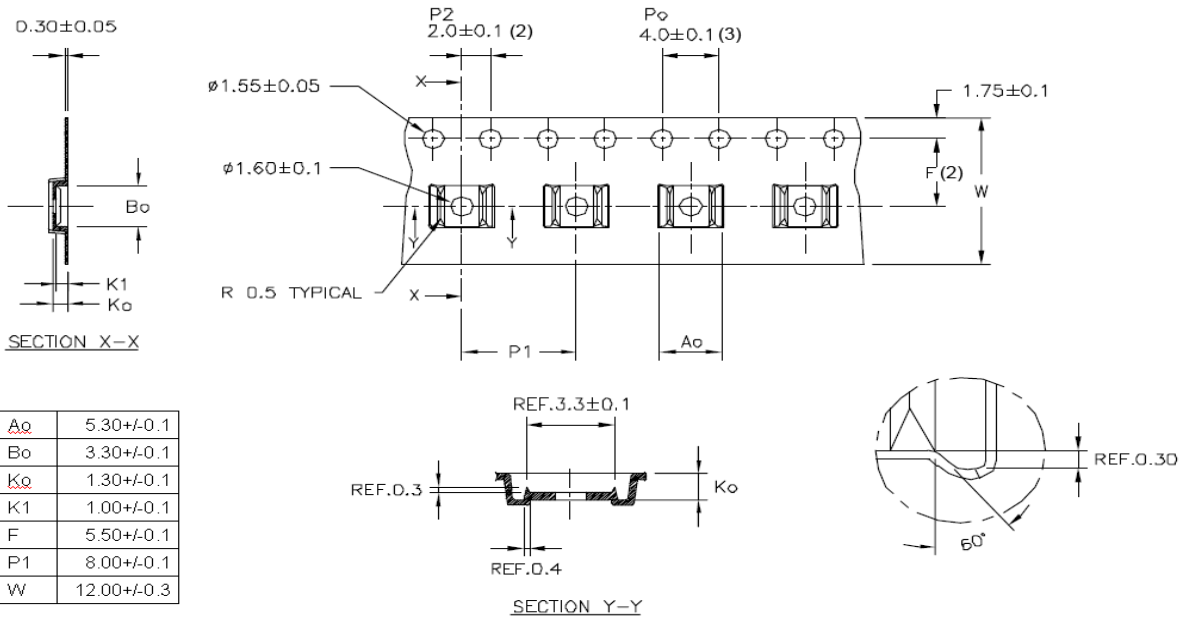
Shipping Reel Dimension



Tape Width	Dia A max	Dim B min	Dia C +.5/-2	Dia D min	Dia N min	Dim W1 +2/-0	Dim W2 max	Dim W3 (LSL - USL)
8	330	1.5	13	20.2	178	8.4	14.4	7.9~10.4
12	330	1.5	13	20.2	178	12.4	18.4	11.9~15.4
16	330	1.5	13	20.2	178	16.4	22.4	15.9~19.4

Tape Dimensions for MSOP

Dimensions are in inches (millimeters) unless otherwise specified.



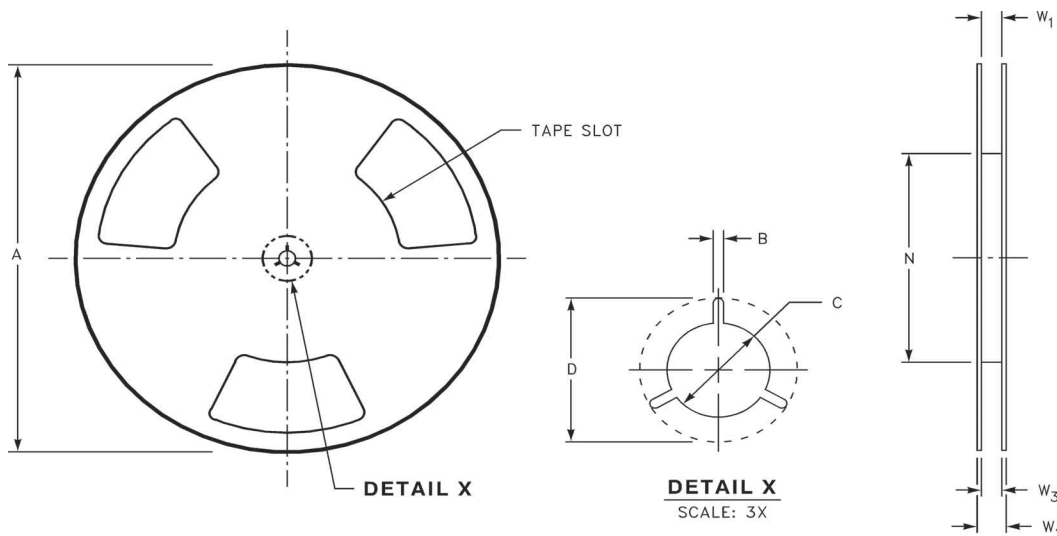
A ₀	5.30±0.1
B ₀	3.30±0.1
K ₀	1.30±0.1
K ₁	1.00±0.1
F	5.50±0.1
P ₁	8.00±0.1
W	12.00±0.3

Notes:

1. All dimensions are in millimeters.
2. Measured from centerline of sprocket hole to centerline of pocket.
3. Cumulative tolerance of ten sprocket holes is ±0.20mm.
4. Other material available.

Reel Dimensions for MSOP

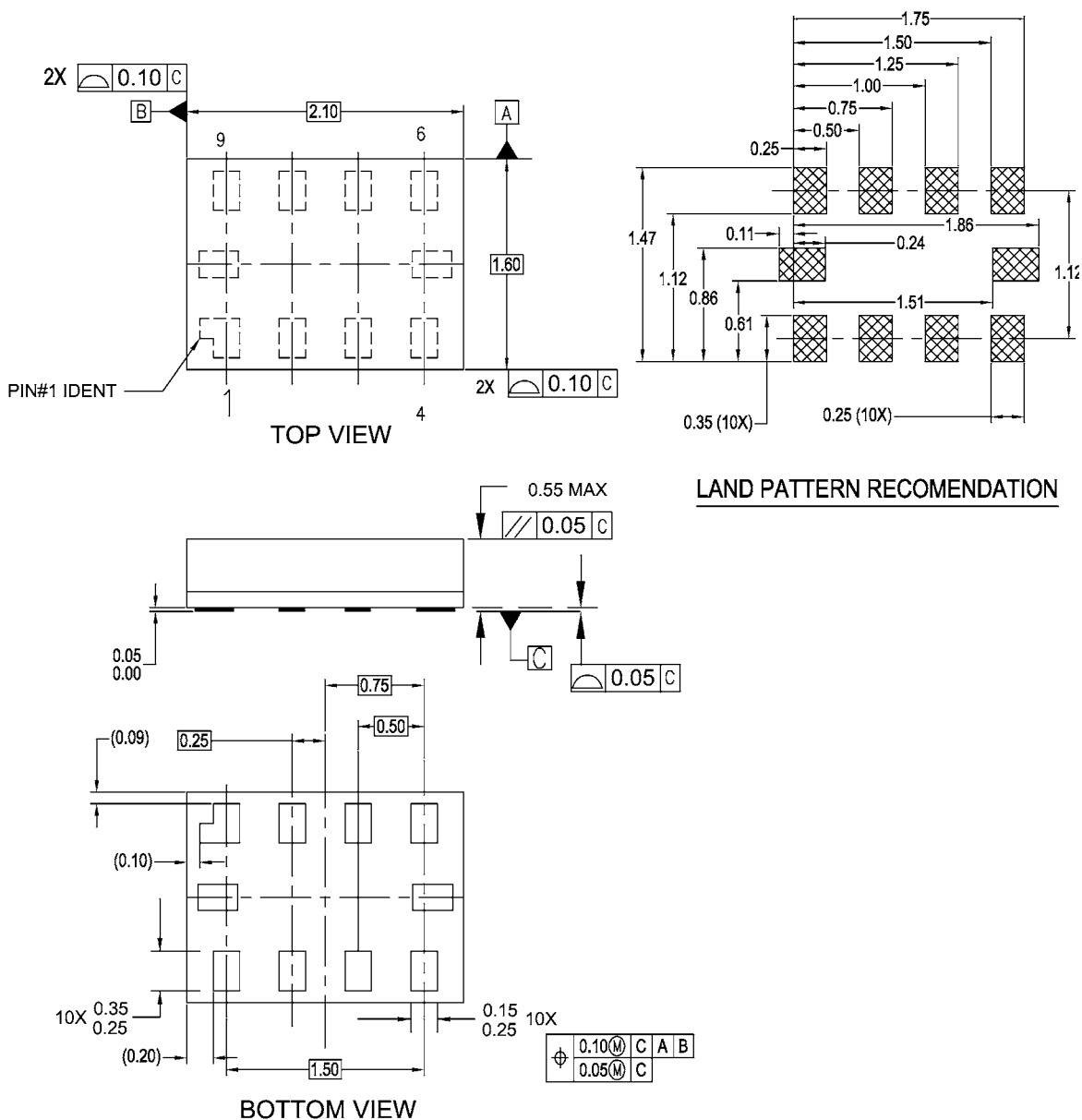
Dimensions are in inches (millimeters) unless otherwise specified.



Tape Size	A	B	C	D	N	W1	W2	W3
(12mm)	13 (330)	0.059 (1.5)	0.512 (13)	0.795 (20.2)	7.008 (178)	0.448 (12.4)	0.724 (18.4)	0.468-0.606 (11.9 -15.4)

Physical Dimensions (Continued)

Dimensions are in millimeters unless otherwise noted.



NOTES:

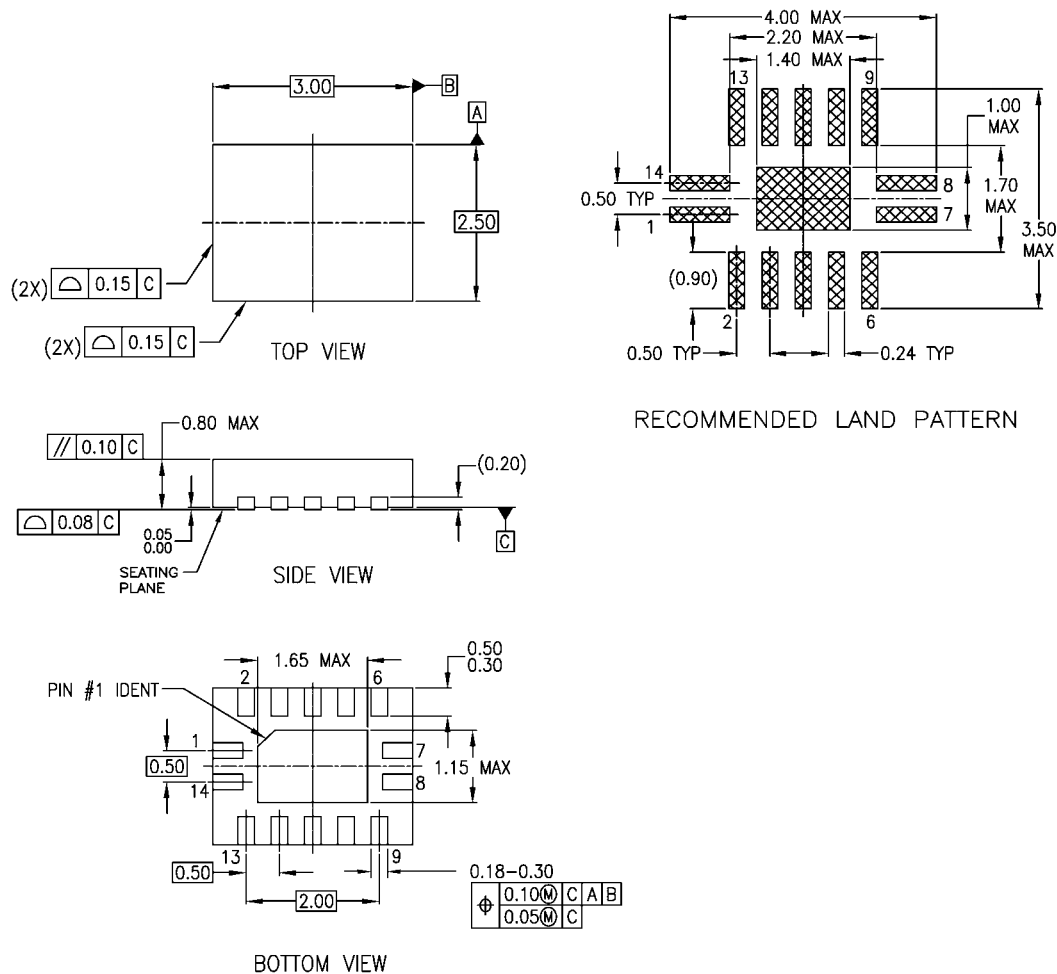
- A. PACKAGE CONFORMS TO JEDEC MO255, VARIATION UABD
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES CONFORMS TO ASME Y14.5M, 1994.

MAC010ARevC

Figure 13. 10-Lead MicroPak, 1.6 x 2.1mm

Physical Dimensions (Continued)

Dimensions are in millimeters unless otherwise noted.



NOTES:

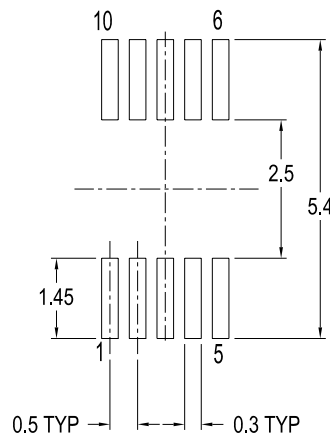
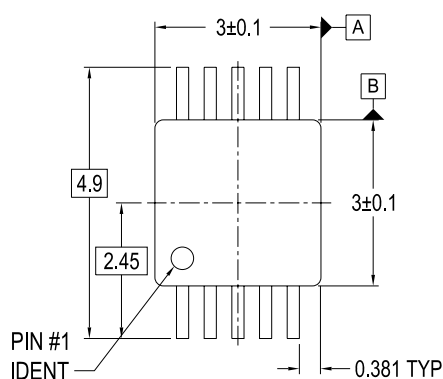
- A. CONFORMS TO JEDEC REGISTRATION MO-241, VARIATION AA
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994

MLP014ArevA

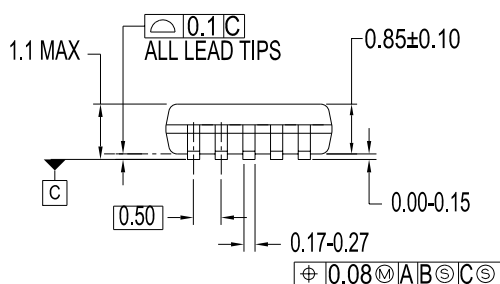
Figure 14. 14-Terminal Depopulated Quad Very-Thin Flat Pack No Leads (DQFN), JEDEC MO-241, 2.5 x 3.0mm

Physical Dimensions (Continued)

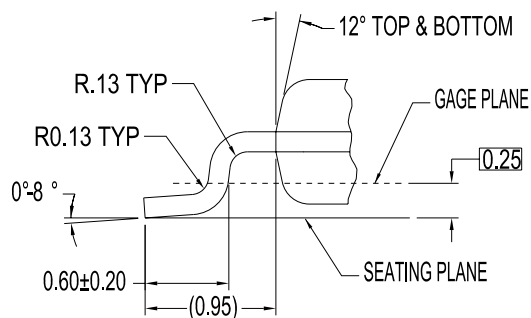
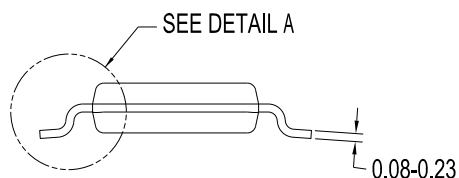
Dimensions are in millimeters unless otherwise noted.



LAND PATTERN RECOMENDATION



DIMENSIONS ARE IN MILLIMETERS



DETAIL A

NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-187, VARIATION BA, REF NOTE 6, DATE 11/00.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.

MUA10AREVA

Figure 15. 10-Lead Molded Small Outline Package (MSOP), JEDEC MO-187, 3.0mm Wide

TRADEMARKS

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

ACEx™	FACT Quiet Series™	OCX™	SILENT SWITCHER®	UniFET™
ActiveArray™	GlobalOptoisolator™	OCXPro™	SMART START™	UltraFET®
Bottomless™	GTO™	OPTOLOGIC®	SPM™	VCX™
Build it Now™	HiSeC™	OPTOPLANAR™	Stealth™	Wire™
CoolFET™	I ² C™	PACMAN™	SuperFET™	
CROSSVOLT™	i-Lo™	POP™	SuperSOT™_3	
DOME™	ImpliedDisconnect™	Power247™	SuperSOT™_6	
EcoSPARK™	IntelliMAX™	PowerEdge™	SuperSOT™_8	
E ² CMOS™	ISOPLANAR™	PowerSaver™	SyncFET™	
EnSigna™	LittleFET™	PowerTrench®	TCM™	
FACT™	MICROCOUPLER™	QFET®	TinyBoost™	
FAST®	MicroFET™	QS™	TinyBuck™	
FAST _r ™	MicroPak™	QT Optoelectronics™	TinyPWM™	
FPS™	MICROWIRE™	Quiet Series™	TinyPower™	
FRFET™	MSX™	RapidConfigure™	TinyLogic®	
	MSXPro™	RapidConnect™	TINYOPTO™	
Across the board. Around the world.™		µSerDes™	TruTranslation™	
The Power Franchise®		ScalarPump™	UHC™	
Programmable Active Droop™				

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PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
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